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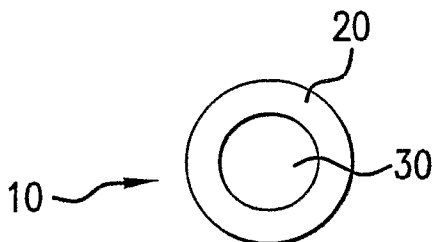
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ning of each regular issue of the PCT Gazette.

(54) Title: IMPROVED INTEGRATED CIRCUIT SUBSTRATE MATERIAL AND METHOD



(57) Abstract: A semiconductor substrate is presented which
is manufactured from hollow, gas-filled glass or ceramic
microspheres, which are bound together in a dried or fired matrix.
The microspheres may be glass-coated microspheres, which are
bound together by sintering the outer layers of glass together. The
semiconductor surface may be smoothed by glazing the surface.



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